
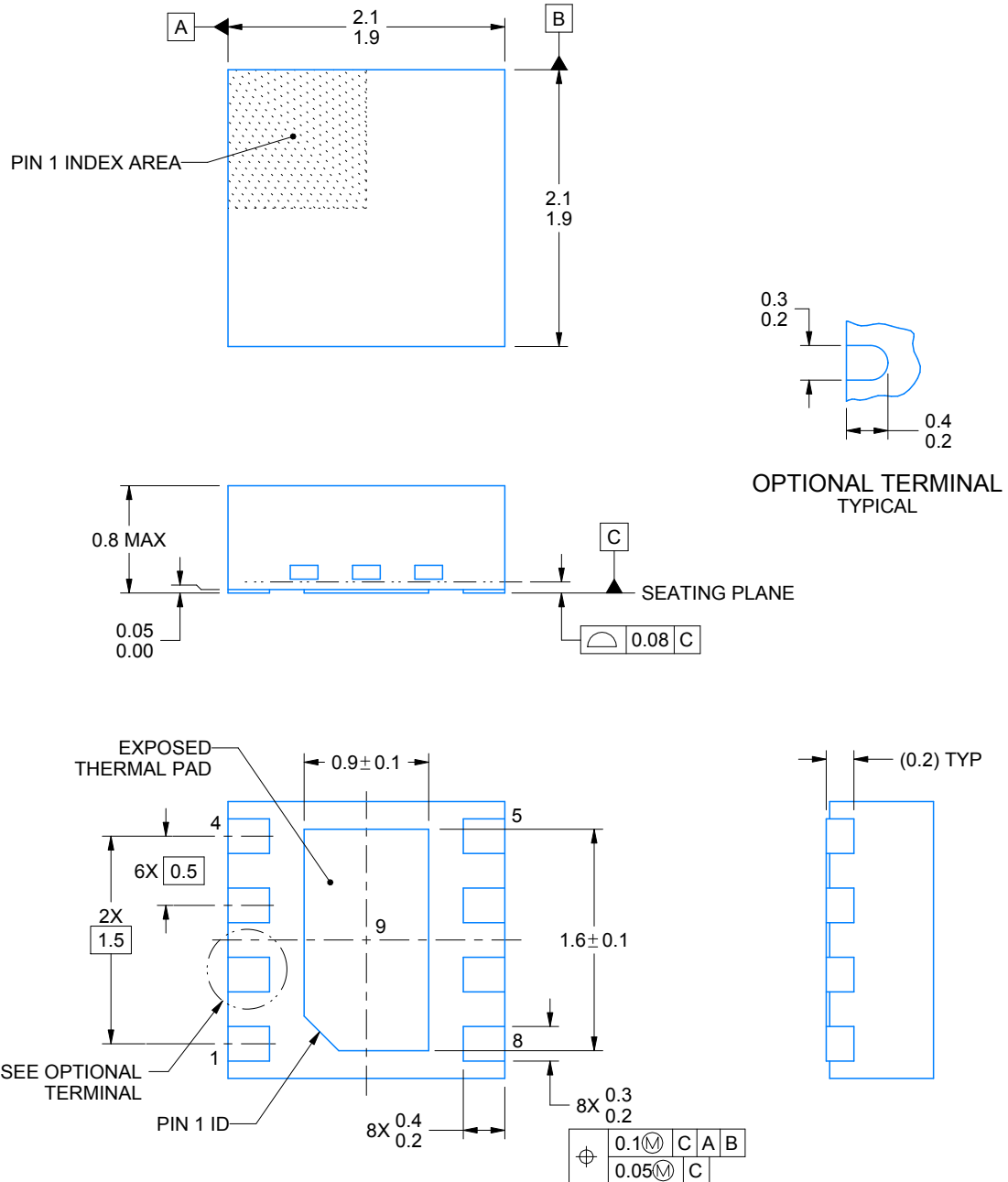
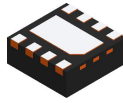


DATA BOOK  
PACKAGE OUTLINE

LEADFRAME EXAMPLE
4211158

DRAFTER:	K.SINCERBOX	DATE:	08/03/2016			DIMENSIONS IN MILLIMETERS		
DESIGNER:		DATE:		<div> <b>TEXAS INSTRUMENTS</b> SEMICONDUCTOR OPERATIONS</div> <div>CODE IDENTITY NUMBER 01295</div>				
CHECKER:		DATE:						
ENGINEER:	H. WIESNER	DATE:	09/19/2017	ePOD, DSG0008A / WSON, 8 PIN, 0.5 MM PITCH				
APPROVED:	D. CHIN & E. LEE	DATE:	09/19/2017					
RELEASED:	WDM	DATE:	09/19/2017					
TEMPLATE INFO:		DATE:		SCALE	SIZE	4218900	REV	PAGE
	EDGE# 4218519		04/07/2016	NTS	A		B	1 OF 5



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## NOTES:

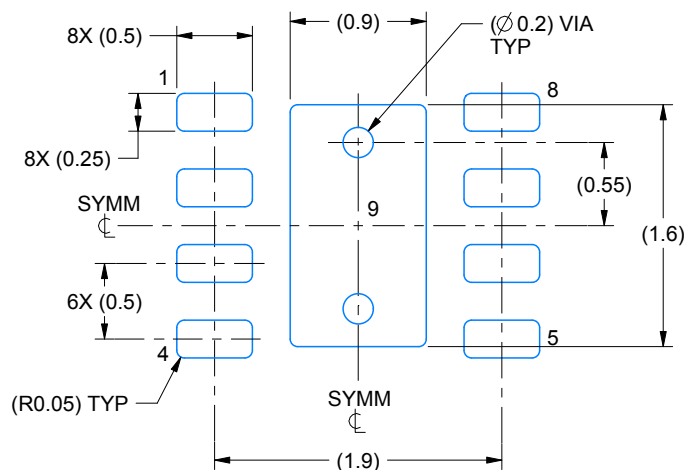
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

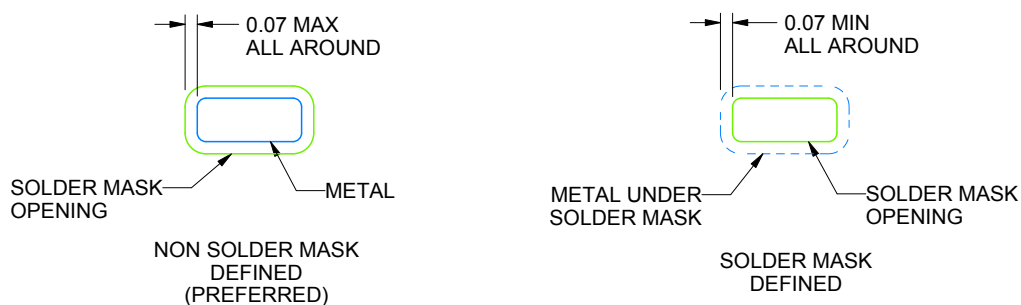
DSG0008A

WSN - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

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NOTES: (continued)

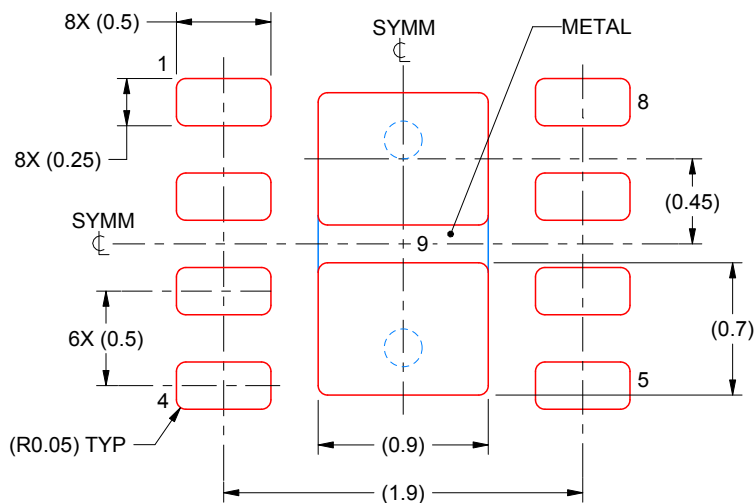
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

## EXAMPLE STENCIL DESIGN

DSG0008A

WSN - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 9:  
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:25X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2159281	08/03/2016	E.REY / K.SINCERBOX
B	REMOVE "OPTIONAL" FROM PIN 1 ID CALLOUT	2168827	09/19/2017	H. WIESNER / K.SINCERBOX